

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Supply Voltage	V _{CC}	50	V
Input Voltage	V _{IN}	-10 to +40	V
Output Current	I _O	50	mA
Collector Current	I _{C(MAX)}	100	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	250	mW
Power Derating above +25°C	P _{der}	2	mW/°C
Thermal Resistance, Junction to Ambient Air (Note 5) (Equivalent to one heated junction of NPN)	R _{θJA}	500	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Off Characteristics (Note 6)						
Collector-Base Breakdown Voltage	BV _{CBO}	50	—	—	V	I _C = 50μA, I _E = 0
Collector-Emitter Breakdown Voltage	BV _{CEO}	50	—	—	V	I _C = 1.0mA, I _B = 0
Collector Cutoff Current	I _{CEX}	—	—	0.5	μA	V _{CE} = 50V, V _{EB(OFF)} = 3.0V
Collector-Base Cut Off Current	I _{CBO}	—	—	0.1	μA	V _{CB} = 50V, I _E = 0
Collector-Emitter Cut Off Current, I _{O(OFF)}	I _{CES}	—	—	0.1	μA	V _{CB} = 50V, I _B = 0
Emitter-Base Cut Off Current	I _{EBO}	—	—	800	μA	V _{EB} = 10V, I _C = 0
Input Off Voltage	V _{I(off)}	0.5	1.16	—	V	V _{CC} = 5V, I _O = 100μA
Input On Voltage	V _{I(on)}	—	—	2.5	V	V _{CC} = 0.3V, I _O = 10mA
On Characteristics (Notes 6 & 7)						
DC Current Gain	h _{FE}	10	—	—	—	V _{CE} = 5V, I _C = 1mA
		15	—	—	—	V _{CE} = 5V, I _C = 2mA
		60	—	—	—	V _{CE} = 5V, I _C = 10mA
		100	—	—	—	V _{CE} = 5V, I _C = 50mA
		90	—	—	—	V _{CE} = 5V, I _C = 70mA
Collector-Emitter Saturation Voltage	V _{CE(sat)}	—	—	0.15	V	I _C = 10mA, I _B = 1mA
		—	—	0.2	V	I _C = 50mA, I _B = 5mA
		—	—	—	—	—
		—	—	0.25	V	I _C = 50mA, I _B = 10mA
		—	—	0.3	V	I _C = 70mA, I _B = 10mA
Base-Emitter Turn-On Voltage	V _{BE(on)}	—	—	0.85	V	V _{CE} = 5V, I _C = 2mA
		—	—	0.95	V	V _{CE} = 5V, I _C = 10mA
Base-Emitter Saturation Voltage	V _{BE(sat)}	—	—	0.98	V	I _C = 10mA, I _B = 1mA
		—	—	1.2	V	I _C = 50mA, I _B = 5mA
Input Current	I _I	—	—	0.88	mA	V _I = 5V
Output On Voltage (Same as V _{CE(sat)})	V _{O(on)}	—	—	0.25	V	I _I = 2.5mA, I _O = 50mA
Input Resistance	R _I	7	10	13	kΩ	—
Resistance Ratio	(R ₂ /R ₁)	0.8	1	1.2	—	—
Small Signal Characteristics						
Current Gain-Bandwidth Product	f _T	—	250	—	MHz	V _{CE} = 10V, I _E = 5mA, f = 1MHz

Notes: 5. For the device mounted on minimum recommended pad layout 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in steady state condition. The entire exposed collector pad is attached to the heatsink.

6. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

7. Guaranteed by design.

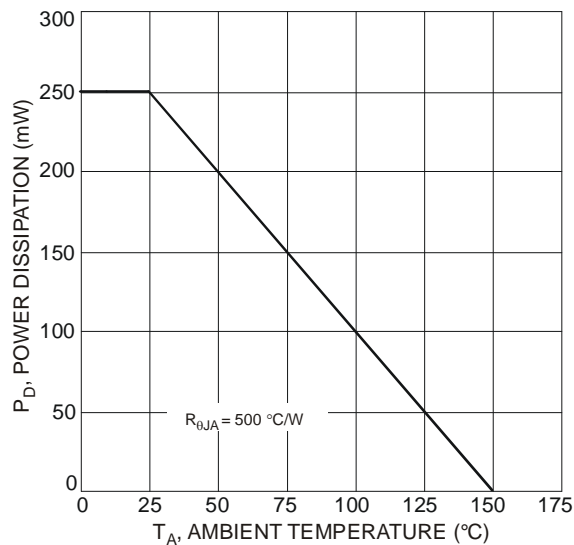


Fig. 1 Power Dissipation vs. Ambient Temperature

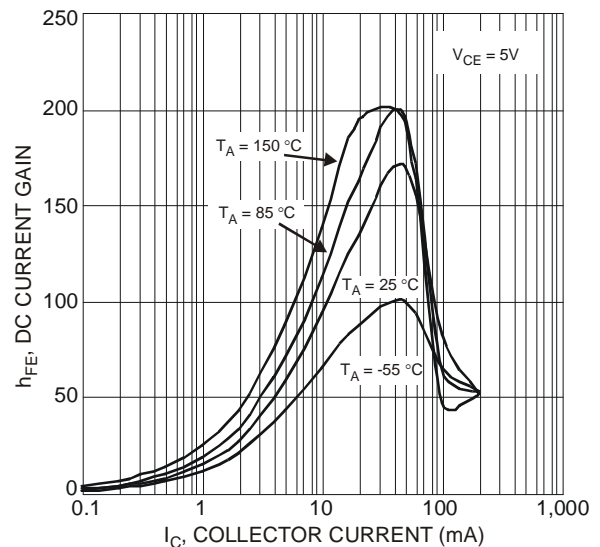


Fig. 2 Typical DC Current Gain vs. Collector Current

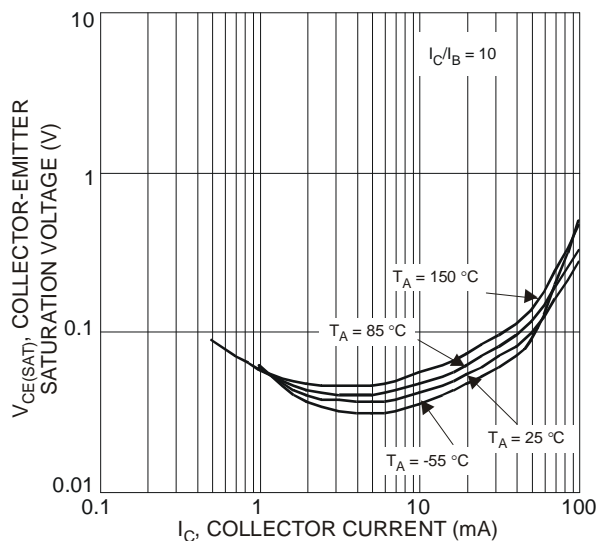


Fig. 3 Typical Collector Emitter Saturation Voltage vs. Collector Current

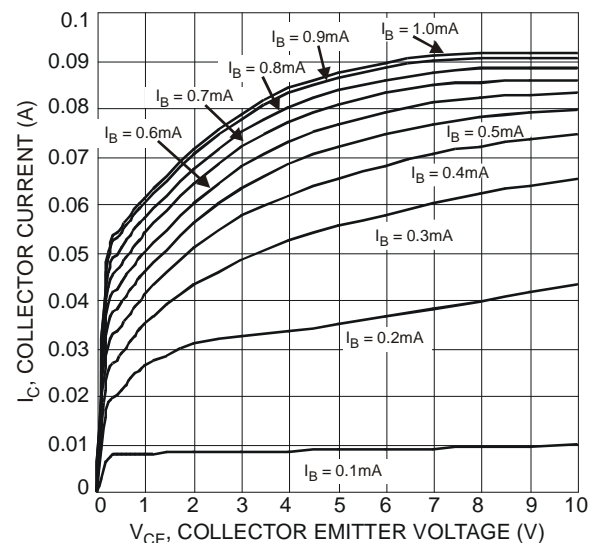


Fig. 4 Typical Collector Current vs. Collector Emitter Voltage

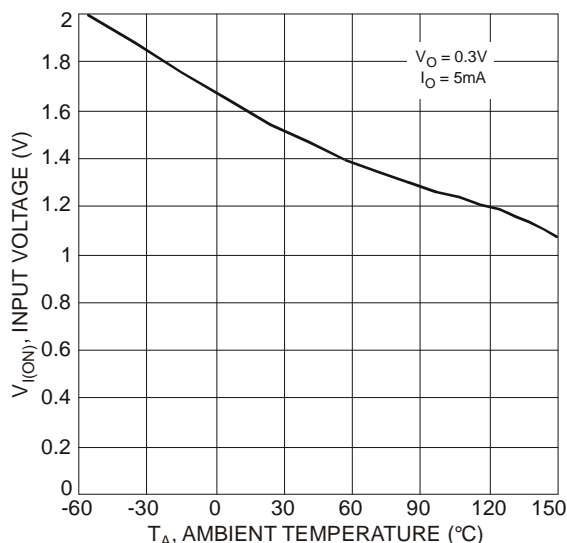


Fig. 5 Typical Input Voltage vs. Ambient Temperature

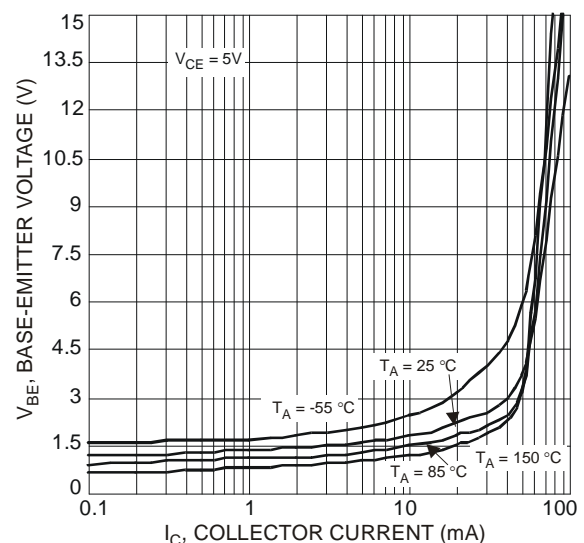


Fig. 6 Typical Base-Emitter Voltage vs. Collector Current

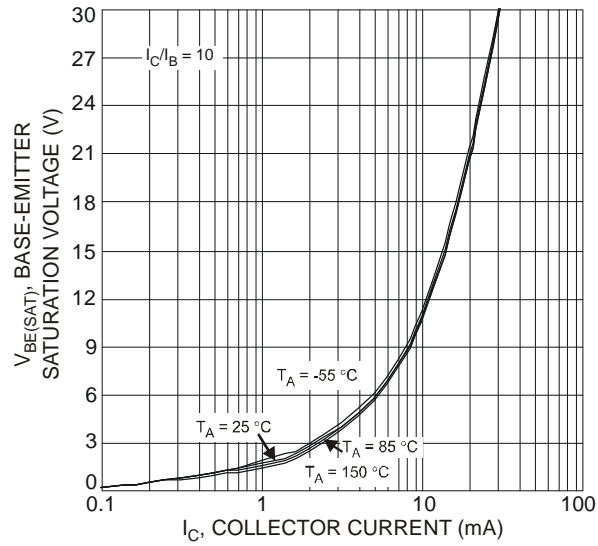
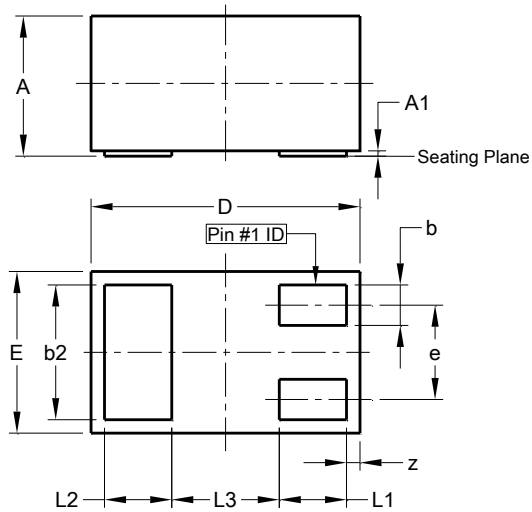


Fig. 7 Typical Base Emitter Saturation Voltage vs. Collector Current

Package Outline Dimensions

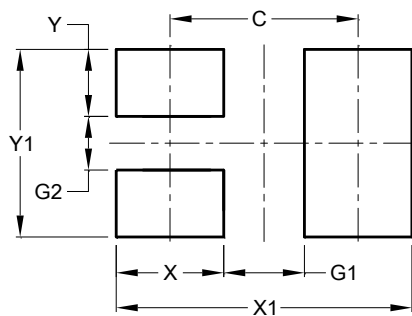
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



X1-DFN1006-3			
Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0.00	0.05	0.03
b	0.10	0.20	0.15
b2	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	-	-	0.35
L1	0.20	0.30	0.25
L2	0.20	0.30	0.25
L3	-	-	0.40
z	0.02	0.08	0.05
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	0.70
G1	0.30
G2	0.20
X	0.40
X1	1.10
Y	0.25
Y1	0.70

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